



<i>flow</i> PIM 0	600 V / 20 A
<div style="border: 1px solid black; padding: 5px; margin-bottom: 10px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Features</p> <ul style="list-style-type: none"> Vincotech clip-in housing Trenchstop™ IGBT3 for low saturation losses Optional w/o BRC </div> <div style="border: 1px solid black; padding: 5px; margin-bottom: 10px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Target Applications</p> <ul style="list-style-type: none"> Industrial drives Embedded drives </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Types</p> <ul style="list-style-type: none"> V23990-P545-A28-PM V23990-P545-A29-PM V23990-P545-B28-PM V23990-P545-B128-PM V23990-P545-B129-PM V23990-P545-C29-PM V23990-P545-D28-PM V23990-P545-C28-PM </div>	<div style="border: 1px solid black; padding: 5px; margin-bottom: 10px;"> <p style="text-align: center; background-color: #ccc; margin: 0;"><i>flow</i> 0 housing</p> <div style="display: flex; justify-content: space-around; align-items: center;"> </div> <div style="display: flex; justify-content: space-around; margin-top: 5px;"> 12mm housing 17mm housing </div> </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Schematic</p> </div>

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Rectifier Diode				
Repetitive peak reverse voltage	V_{RRM}		1600	V
DC forward current	I_{FAV}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	34	A
Surge (non-repetitive) forward current	I_{FSM}	$t_p = 10\text{ ms}$ 50 Hz half sine wave $T_j = 150\text{ °C}$	200	A
I^2t -value	I^2t		200	A ² s
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	43	W
Maximum Junction Temperature	T_{jmax}		150	°C
Inverter Switch				
Collector-emitter breakdown voltage	V_{CE}		600	V
DC collector current	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	26	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	60	A
Turn off safe operating area		$V_{CE} \leq 1200V, T_j \leq T_{op, max}$	60	A
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	56	W
Gate-emitter peak voltage	V_{GE}		±20	V
Short circuit ratings	t_{SC}	$T_j \leq 150\text{ °C}$	6	µs
	V_{CC}	$V_{GE} = 15\text{ V}$	360	V
Maximum Junction Temperature	T_{jmax}		175	°C

**Maximum Ratings** $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
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Inverter Diode

Peak Repetitive Reverse Voltage	V_{RRM}		600	V
DC forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	21	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	40	A
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	37	W
Maximum Junction Temperature	T_{jmax}		175	°C

Brake Switch

Collector-emitter breakdown voltage	V_{CE}		600	V
DC collector current	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	21	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	45	A
Turn off safe operating area		$V_{CE} \leq 1200V$, $T_j \leq T_{op\ max}$	45	A
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	52	W
Gate-emitter peak voltage	V_{GE}		± 20	V
Short circuit ratings	t_{SC} V_{CC}	$T_j \leq 150\text{ °C}$ $V_{GE} = 15\text{ V}$	6 360	μs V
Maximum Junction Temperature	T_{jmax}		175	°C

Brake Diode

Peak Repetitive Reverse Voltage	V_{RRM}		600	V
DC forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	18	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	30	A
Power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	35	W
Maximum Junction Temperature	T_{jmax}		175	°C

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{op}		-40...+($T_{jmax} - 25$)	°C

Isolation Properties

Isolation voltage	V_{is}	$t = 2s$ DC voltage	4000	V
Creepage distance			min 12,7	mm
Clearance		12 mm / 17 mm housing	9,29 / min 12,7	mm
Comparative tracking index	CTI		>200	



Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GE} [V]	V_{GS} [V]	V_{CE} [V]	V_{DS} [V]	I_C [A] I_F [A] I_D [A]	T_j [°C]	Min	Typ	

Rectifier Diode

Forward voltage	V_F				25	25 125	0,8	1,22 1,20	1,45	V
Threshold voltage (for power loss calc. only)	V_{to}				25	25 125		0,95 0,81		V
Slope resistance (for power loss calc. only)	r_t				25	25 125		10 20		mΩ
Reverse current	I_r			1600		25 145			0,05 1,1	mA
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,61		K/W

Inverter Switch

Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,00029	25		5	5,8	6,5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		20	25 125	1	1,55 1,75	2,2		V
Collector-emitter cut-off current incl. Diode	I_{CES}		0	600		25			0,0011		mA
Gate-emitter leakage current	I_{GES}		20	0		25			300		nA
Integrated Gate resistor	R_{gint}							none			Ω
Turn-on delay time	$t_{d(on)}$	$R_{goff} = 8$ Ω $R_{gonn} = 16$ Ω	+15/0	300	20	25			15		ns
Rise time	t_r					125			12		
Turn-off delay time	$t_{d(off)}$					25			198		
Fall time	t_f					125			212		
Turn-on energy loss	E_{on}					25			100		
Turn-off energy loss	E_{off}	125			104		0,31 0,43			mWs	
Input capacitance	C_{ies}							1100			pF
Output capacitance	C_{oss}	$f = 1$ MHz	0	25		25		71			
Reverse transfer capacitance	C_{rss}							32			
Gate charge	Q_G		±15	480	20	25		120			nC
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,70			K/W

Inverter Diode

Diode forward voltage	V_F				20	25 125	1,25	1,81 1,76	1,95		V		
Peak reverse recovery current	I_{RRM}	$R_{gonn} = 16$ Ω	+15/0	300	20	25		19			A		
Reverse recovery time	t_{rr}					125			33 192				ns
Reverse recovered charge	Q_{rr}					25			0,45 1,35				μC
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					125			1454 1052				A/μs
Reverse recovered energy	E_{rec}					25			0,06 0,27				mWs
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						2,60			K/W		



Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GE} [V]	V_{CE} [V]	V_{GS} [V]	V_r [V] V_{CE} [V] V_{DS} [V]	I_C [A] I_F [A] I_D [A]	T_j [°C]	Min	Typ	

Brake Switch

Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$				0,00021	25	5	5,8	6,5	V
Collector-emitter saturation voltage	V_{CESat}		15			15	25 125	1,1	1,79 2,08	1,9	V
Collector-emitter cut-off incl diode	I_{CES}		0	600			25			0,00085	mA
Gate-emitter leakage current	I_{GES}		20	0			25			300	nA
Integrated Gate resistor	R_{gint}								none		Ω
Turn-on delay time	$t_{d(on)}$	$R_{goff} = 8 \Omega$ $R_{gon} = 16 \Omega$	+15/0	300	15	15	25			15	ns
Rise time	t_r						125			11	
Turn-off delay time	$t_{d(off)}$						25			14	
Fall time	t_f						125			128 145	
Turn-on energy loss	E_{on}						25			91	
Turn-off energy loss	E_{off}						125			94	
Input capacitance	C_{ies}	$f = 1 \text{ MHz}$	0	25	25	25			860		pF
Output capacitance	C_{oss}								55		
Reverse transfer capacitance	C_{rss}								24		
Gate charge	Q_G		± 15	480	15	25			87		nC
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{monte} = 3,4 \text{ W/mK}$ (PSX)							1,83		K/W

Brake Diode

Diode forward voltage	V_F					15	25 125	1,25	1,86 1,75	1,95	V
Reverse leakage current	I_r			600			25			27	μA
Peak reverse recovery current	I_{RRM}	$R_{gon} = 16 \Omega$	+15/0	300	15	15	25			14	A
Reverse recovery time	t_{rr}						125			15	
Reverse recovered charge	Q_{rr}						25			128 201	
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$						125			0,52 1,02	
Reverse recovery energy	E_{rec}						25			1307 657	
							125			0,10 0,21	
Thermal resistance junction to sink	$R_{th(j-s)}$	$\lambda_{monte} = 3,4 \text{ W/mK}$ (PSX)							2,75		K/W

Thermistor

Rated resistance	R						25		22000		Ω
Deviation of R100	$\Delta_{R/R}$	$R_{100} = 1484 \Omega$					100	-5		5	%
Power dissipation	P						25		210		mW
Power dissipation constant							25		3,5		mW/K
B-value	$B_{(25/50)}$	Tol. $\pm 3\%$					25				K
B-value	$B_{(25/100)}$	Tol. $\pm 3\%$					25		4000		K
Vincotech NTC Reference							25			A	

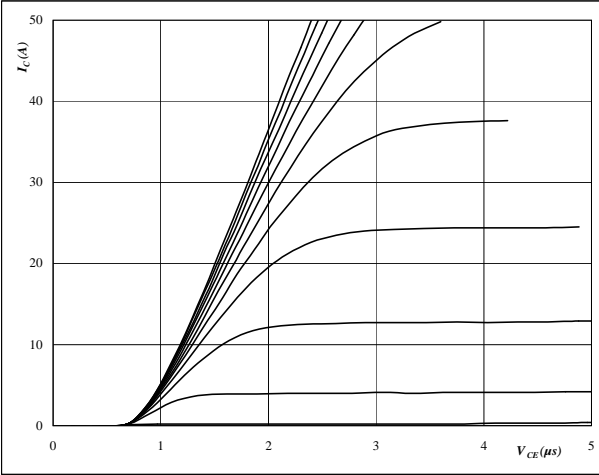


Inverter Charateristics

Figure 1 IGBT

Typical output characteristics

$I_C = f(V_{CE})$



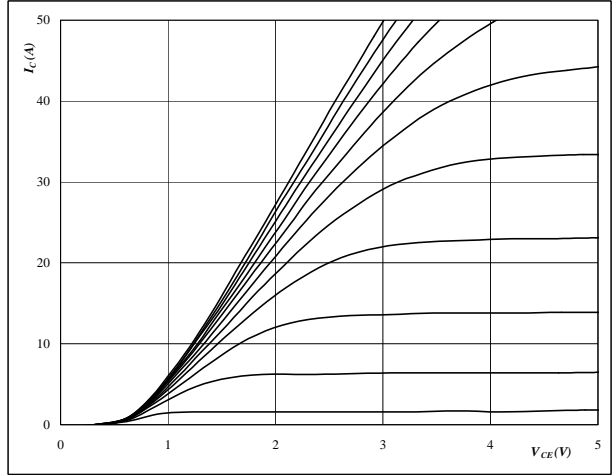
At

$t_p = 250 \mu s$
 $T_j = 25 \text{ }^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 2 IGBT

Typical output characteristics

$I_C = f(V_{CE})$



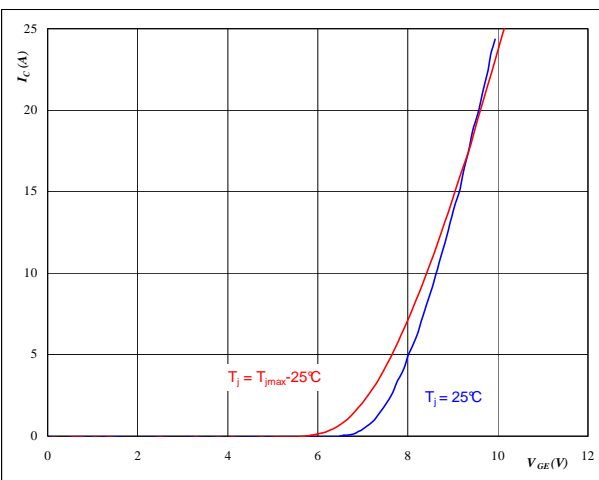
At

$t_p = 250 \mu s$
 $T_j = 125 \text{ }^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 3 IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$



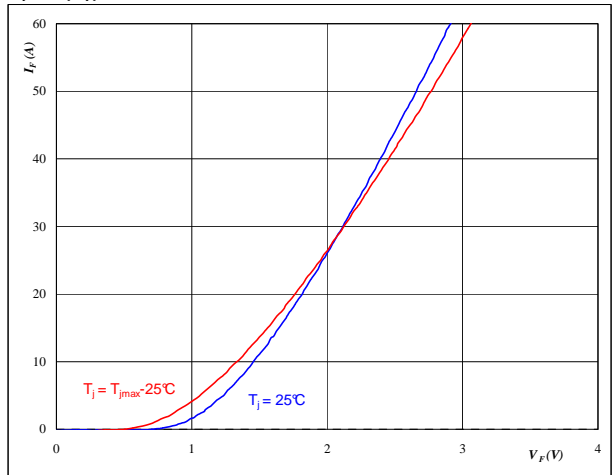
At

$t_p = 250 \mu s$
 $V_{CE} = 10 V$

Figure 4 FWD

Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$



At

$t_p = 250 \mu s$

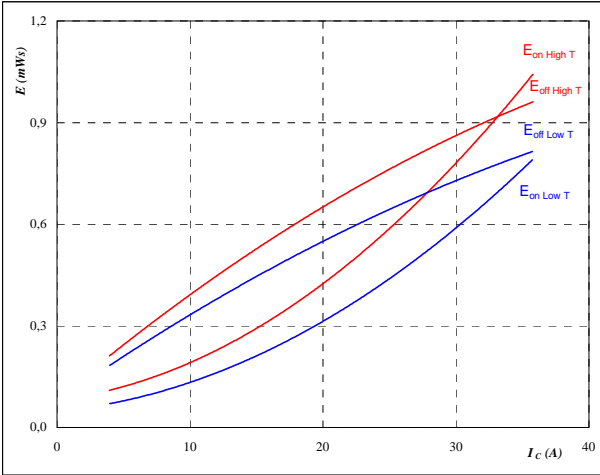


Inverter Charateristics

Figure 5 IGBT

Typical switching energy losses
as a function of collector current

$E = f(I_C)$



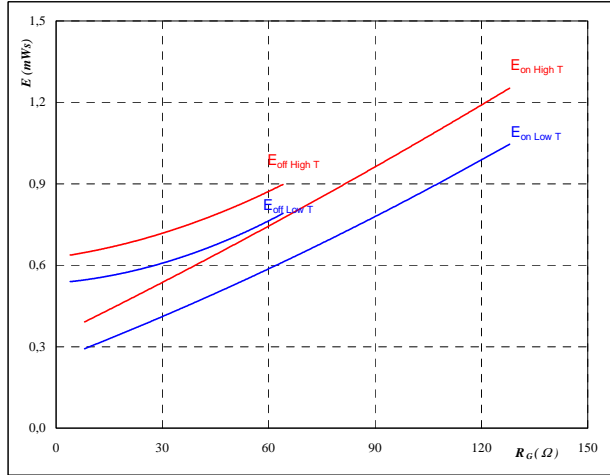
With an inductive load at

- $T_j = 25/125$ °C
- $V_{CE} = 300$ V
- $V_{GE} = 15$ V
- $R_{gon} = 16$ Ω
- $R_{goff} = 8$ Ω

Figure 6 IGBT

Typical switching energy losses
as a function of gate resistor

$E = f(R_G)$



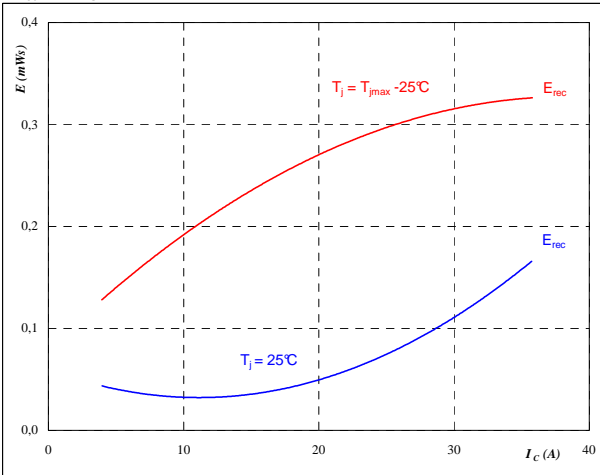
With an inductive load at

- $T_j = 25/125$ °C
- $V_{CE} = 300$ V
- $V_{GE} = 15$ V
- $I_C = 20$ A

Figure 7 FWD

Typical reverse recovery energy loss
as a function of collector current

$E_{rec} = f(I_C)$



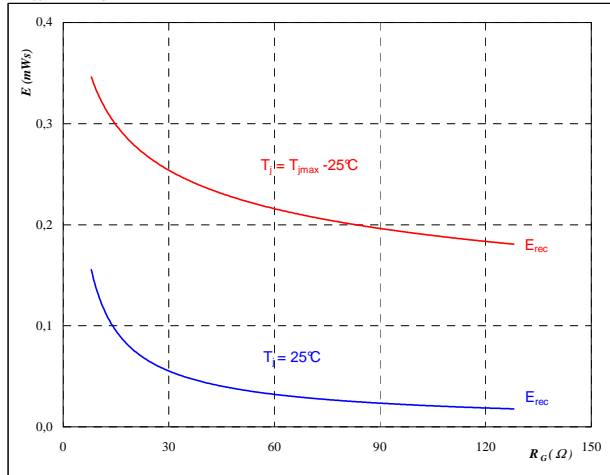
With an inductive load at

- $T_j = 25/125$ °C
- $V_{CE} = 300$ V
- $V_{GE} = 15$ V
- $R_{gon} = 16$ Ω

Figure 8 FWD

Typical reverse recovery energy loss
as a function of gate resistor

$E_{rec} = f(R_G)$



With an inductive load at

- $T_j = 25/125$ °C
- $V_{CE} = 300$ V
- $V_{GE} = 15$ V
- $I_C = 20$ A

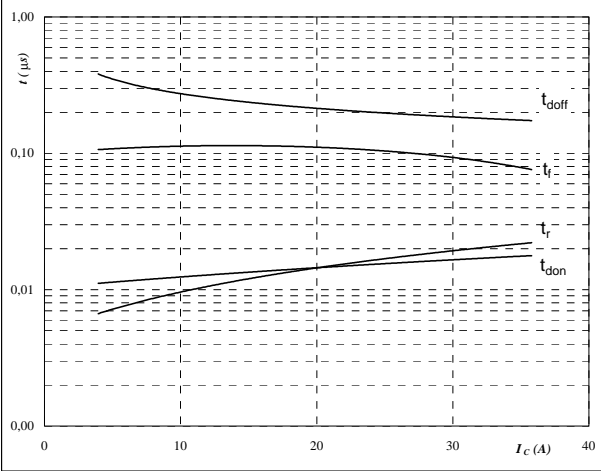


Inverter Characteristics

Figure 9 IGBT

Typical switching times as a function of collector current

$t = f(I_C)$



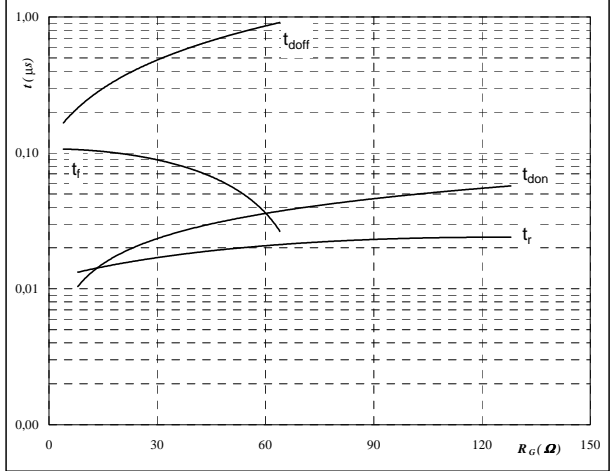
With an inductive load at

$T_j =$	125	°C
$V_{CE} =$	300	V
$V_{GE} =$	15	V
$R_{gon} =$	16	Ω
$R_{goff} =$	8	Ω

Figure 10 IGBT

Typical switching times as a function of gate resistor

$t = f(R_G)$



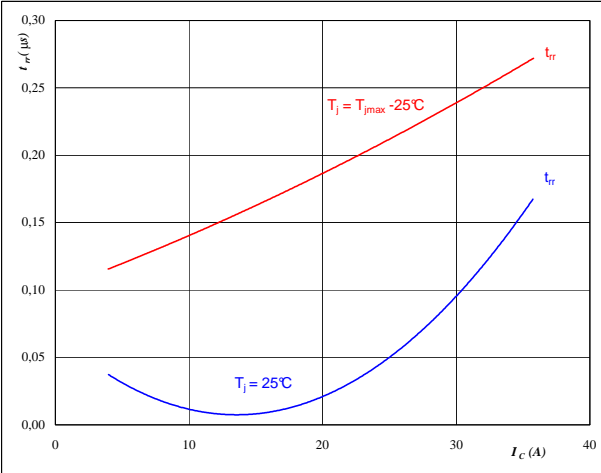
With an inductive load at

$T_j =$	125	°C
$V_{CE} =$	300	V
$V_{GE} =$	15	V
$I_C =$	20	A

Figure 11 FWD

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



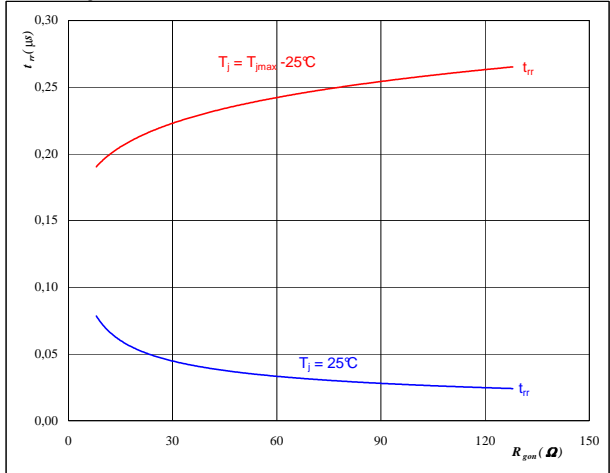
At

$T_j =$	25/125	°C
$V_{CE} =$	300	V
$V_{GE} =$	15	V
$R_{gon} =$	16	Ω

Figure 12 FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



At

$T_j =$	25/125	°C
$V_R =$	300	V
$I_F =$	20	A
$V_{GE} =$	15	V

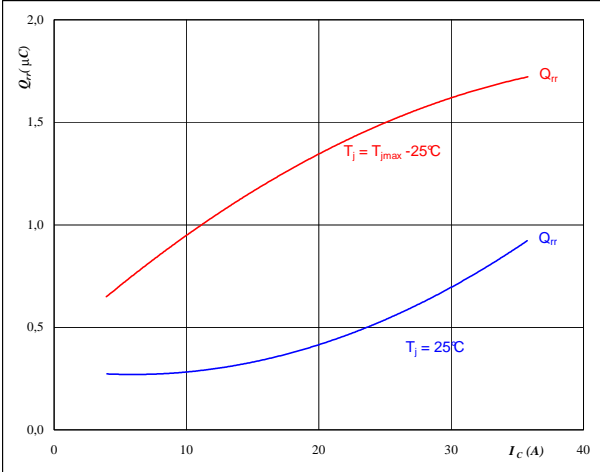


Inverter Charateristics

Figure 13 FWD

Typical reverse recovery charge as a function of collector current

$Q_{rr} = f(I_c)$

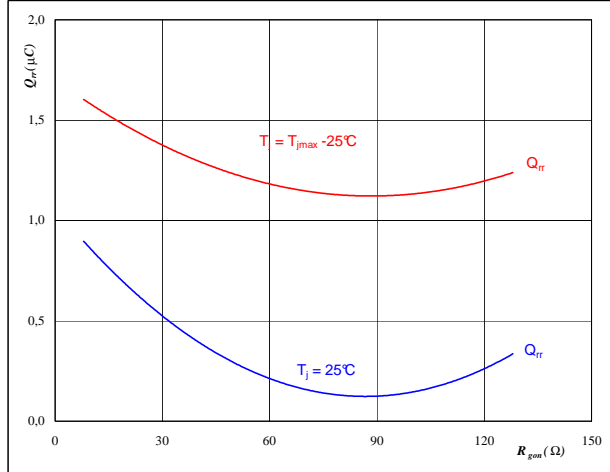


At
 $T_j = 25/125$ °C
 $V_{CE} = 300$ V
 $V_{GE} = 15$ V
 $R_{gon} = 16$ Ω

Figure 14 FWD

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$Q_{rr} = f(R_{gon})$

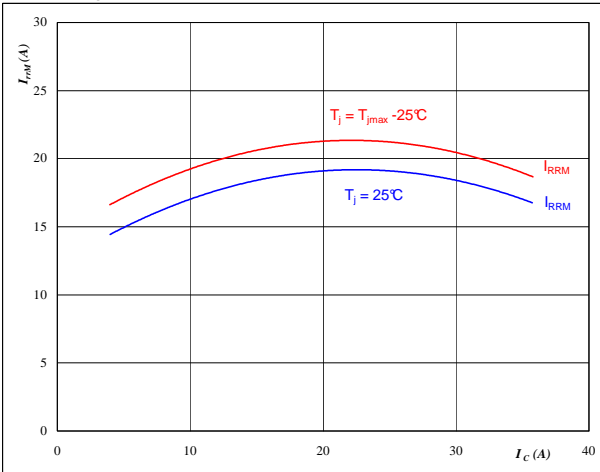


At
 $T_j = 25/125$ °C
 $V_R = 300$ V
 $I_F = 20$ A
 $V_{GE} = 15$ V

Figure 15 FWD

Typical reverse recovery current as a function of collector current

$I_{RRM} = f(I_c)$

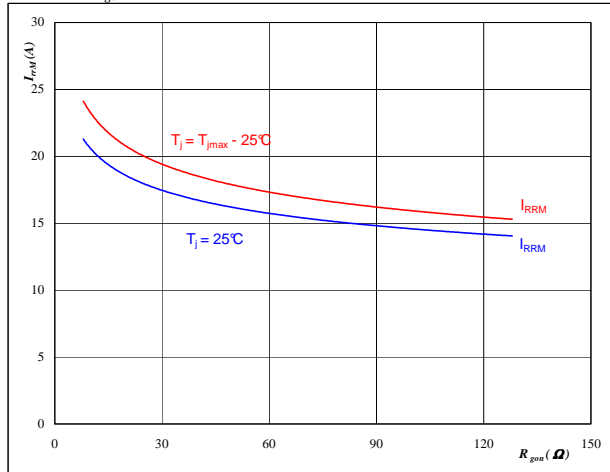


At
 $T_j = 25/125$ °C
 $V_{CE} = 300$ V
 $V_{GE} = 15$ V
 $R_{gon} = 16$ Ω

Figure 16 FWD

Typical reverse recovery current as a function of IGBT turn on gate resistor

$I_{RRM} = f(R_{gon})$



At
 $T_j = 25/125$ °C
 $V_R = 300$ V
 $I_F = 20$ A
 $V_{GE} = 15$ V

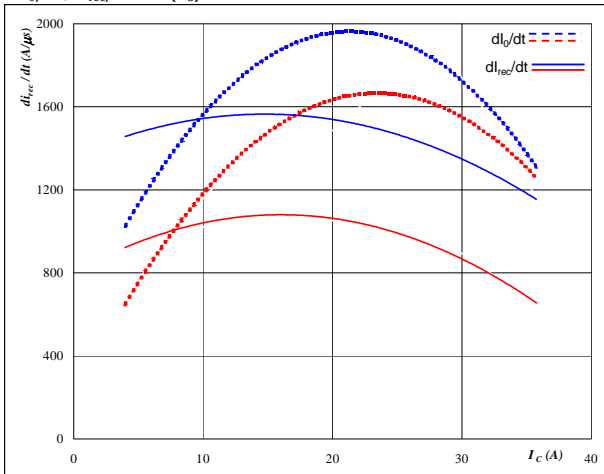


Inverter Characteristics

Figure 17 FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

$$dI_0/dt, dI_{rec}/dt = f(I_C)$$

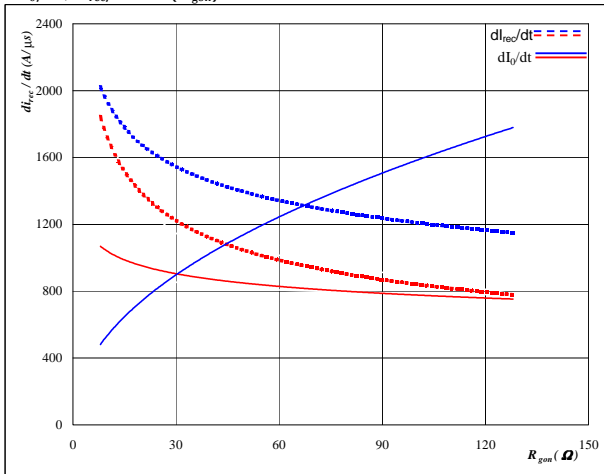


At
 $T_j = 25/125$ °C
 $V_{CE} = 300$ V
 $V_{GE} = 15$ V
 $R_{gon} = 16$ Ω

Figure 18 FWD

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$$dI_0/dt, dI_{rec}/dt = f(R_{gon})$$

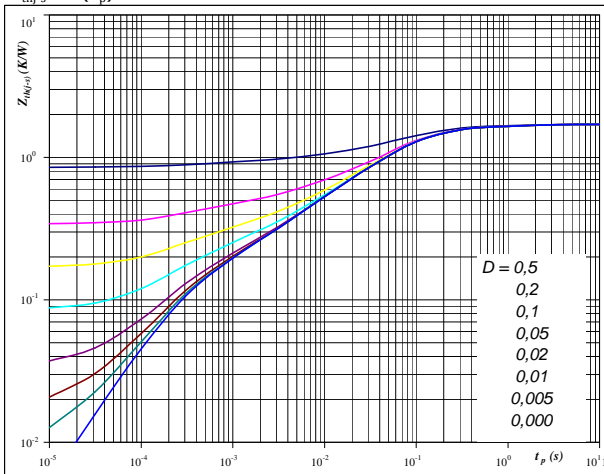


At
 $T_j = 25/125$ °C
 $V_R = 300$ V
 $I_F = 20$ A
 $V_{GE} = 15$ V

Figure 19 IGBT

IGBT transient thermal impedance as a function of pulse width

$$Z_{thj-s} = f(t_p)$$



At
 $D = t_p / T$
 $R_{thjH} = 1,70$ K/W

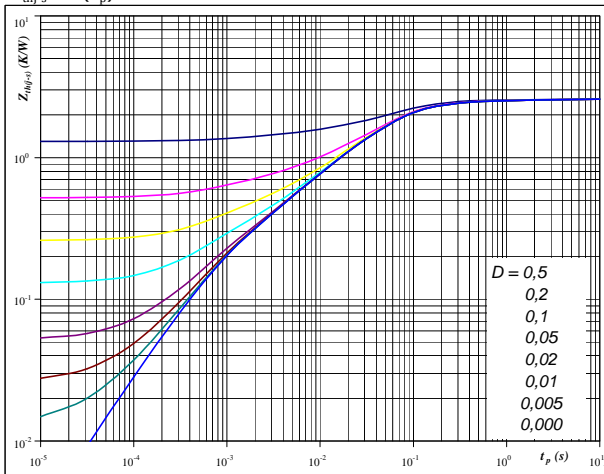
IGBT thermal model values

R (K/W)	Tau (s)
9,97E-02	1,34E+00
3,46E-01	1,70E-01
8,15E-01	5,34E-02
2,54E-01	7,74E-03
7,70E-02	1,33E-03
1,09E-01	2,63E-04

Figure 20 FWD

FWD transient thermal impedance as a function of pulse width

$$Z_{thj-s} = f(t_p)$$



At
 $D = t_p / T$
 $R_{thjH} = 2,60$ K/W

FWD thermal model values

R (K/W)	Tau (s)
6,56E-02	4,59E+00
1,58E-01	5,68E-01
8,97E-01	8,42E-02
1,05E+00	3,29E-02
2,75E-01	4,96E-03
1,51E-01	7,65E-04

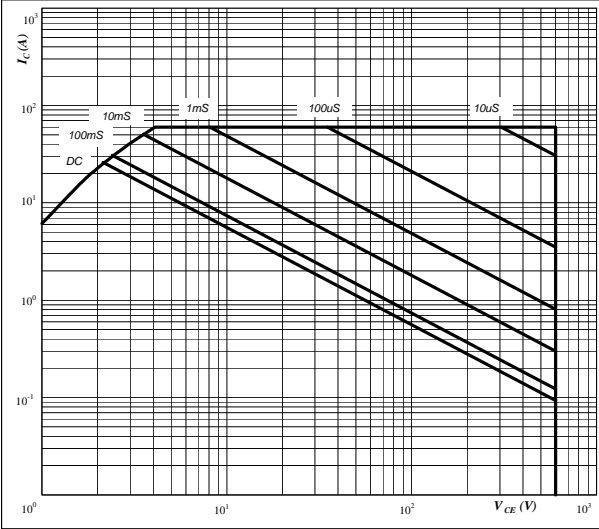


Inverter Characteristics

Figure 25 IGBT

Safe operating area as a function of collector-emitter voltage

$I_C = f(V_{CE})$

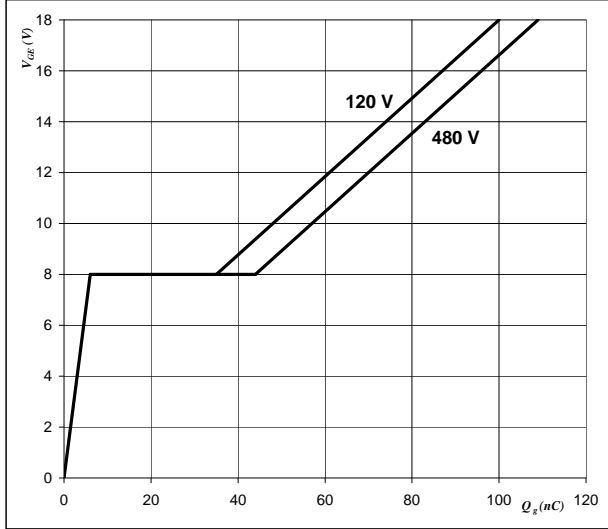


At
 $D =$ single pulse
 $T_s =$ 80 °C
 $V_{GE} =$ 15 V
 $T_j = T_{jmax}$

Figure 26 IGBT

Gate voltage vs Gate charge

$V_{GE} = f(Q_G)$

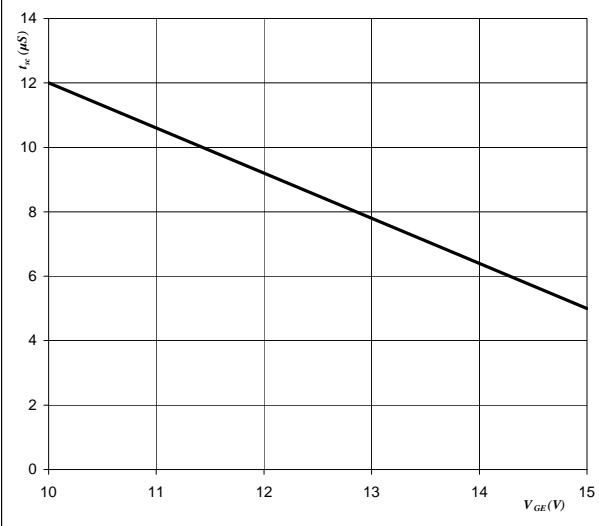


At
 $I_C =$ 20 A

Figure 27 IGBT

Short circuit withstand time as a function of gate-emitter voltage

$t_{sc} = f(V_{GE})$

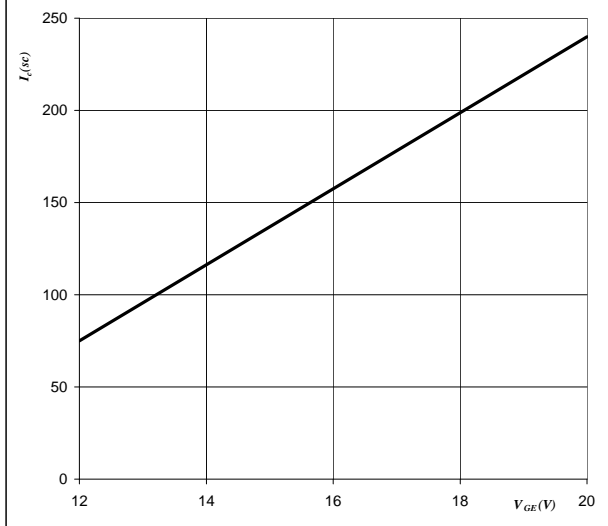


At
 $V_{CE} =$ 600 V
 $T_j \leq$ 175 °C

Figure 28 IGBT

Typical short circuit collector current as a function of gate-emitter voltage

$I_{sc} = f(V_{GE})$

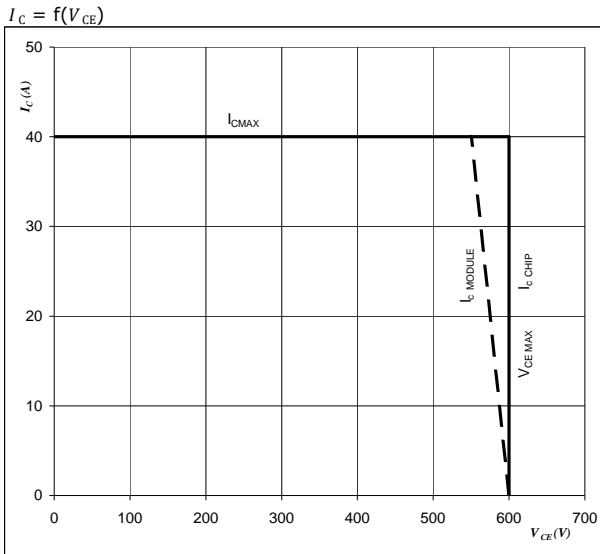


At
 $V_{CE} \leq$ 600 V
 $T_j =$ 175 °C



Inverter Characteristics

Figure 29 IGBT
Reverse bias safe operating area



At

$$T_j = T_{jmax} - 25 \text{ } ^\circ\text{C}$$

Switching mode : 3phase SPWM

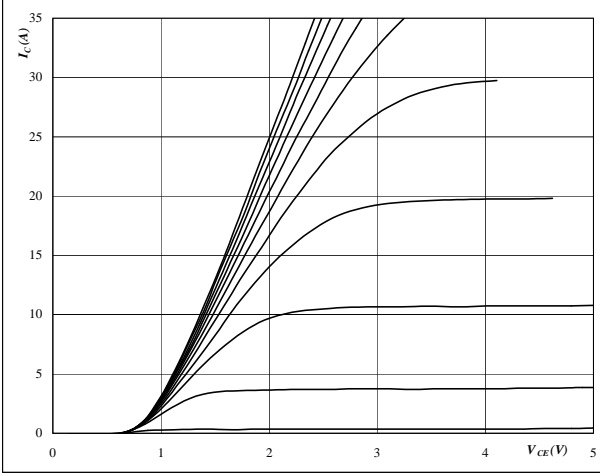


Brake Characteristics

Figure 1 IGBT

Typical output characteristics

$I_C = f(V_{CE})$



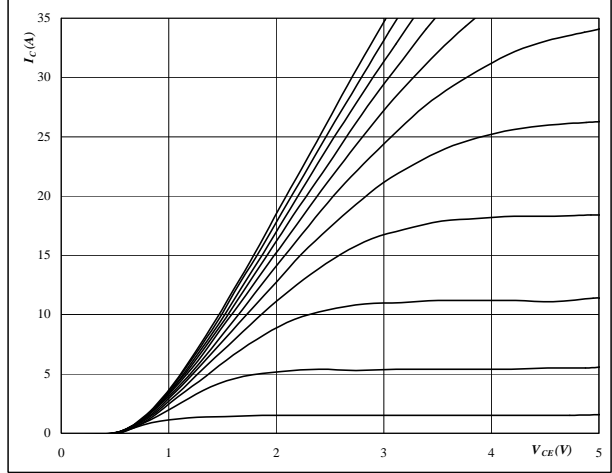
At

$t_p = 250 \mu s$
 $T_j = 25 \text{ } ^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 2 IGBT

Typical output characteristics

$I_C = f(V_{CE})$



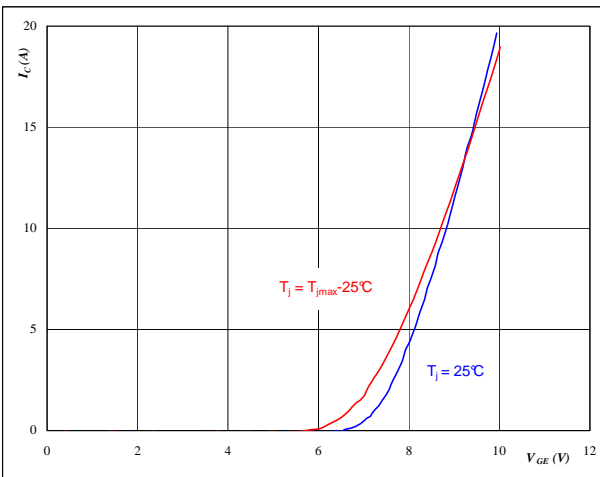
At

$t_p = 250 \mu s$
 $T_j = 125 \text{ } ^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 3 IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$



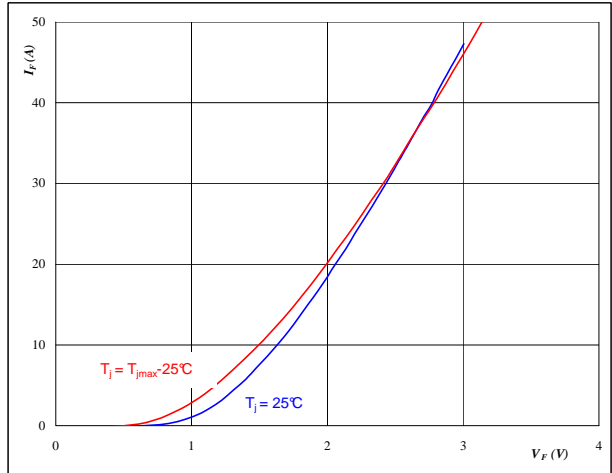
At

$t_p = 250 \mu s$
 $V_{CE} = 10 V$

Figure 4 IGBT

Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$



At

$t_p = 250 \mu s$

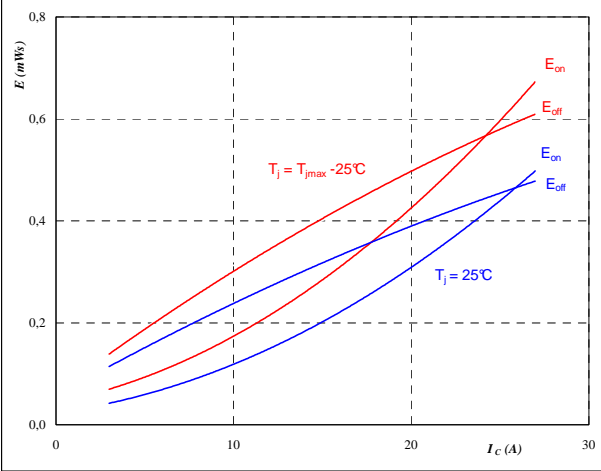


Brake Characteristics

Figure 5 IGBT

Typical switching energy losses
as a function of collector current

$E = f(I_C)$



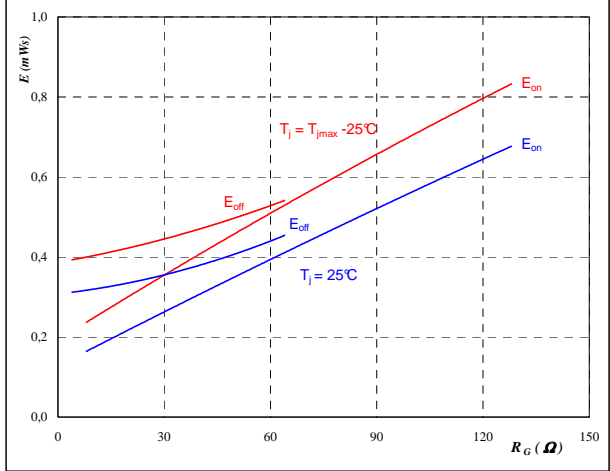
With an inductive load at

- $T_j = 25/125$ °C
- $V_{CE} = 300$ V
- $V_{GE} = 15$ V
- $R_{gon} = 16$ Ω
- $R_{goff} = 8$ Ω

Figure 6 IGBT

Typical switching energy losses
as a function of gate resistor

$E = f(R_G)$



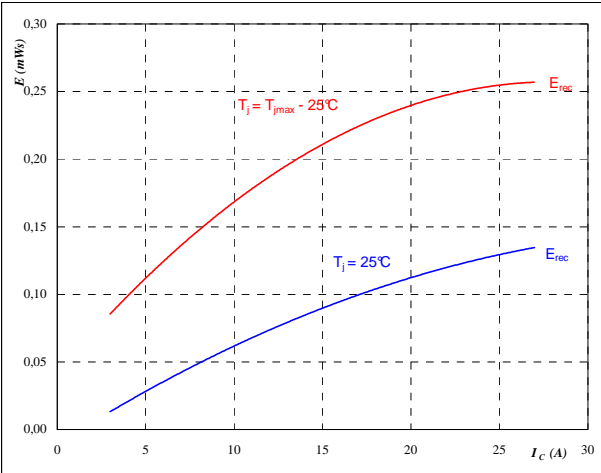
With an inductive load at

- $T_j = 25/125$ °C
- $V_{CE} = 300$ V
- $V_{GE} = 15$ V
- $I_C = 15$ A

Figure 7 FWD

Typical reverse recovery energy loss
as a function of collector current

$E_{rec} = f(I_C)$



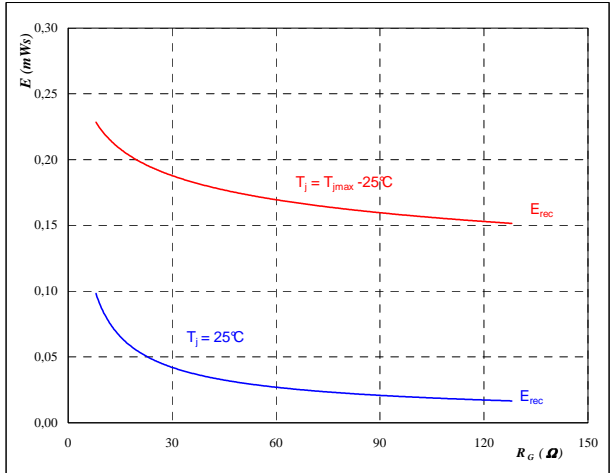
With an inductive load at

- $T_j = 25/125$ °C
- $V_{CE} = 300$ V
- $V_{GE} = 15$ V
- $R_{gon} = 16$ Ω

Figure 8 FWD

Typical reverse recovery energy loss
as a function of gate resistor

$E_{rec} = f(R_G)$



With an inductive load at

- $T_j = 25/125$ °C
- $V_{CE} = 300$ V
- $V_{GE} = 15$ V
- $I_C = 15$ A

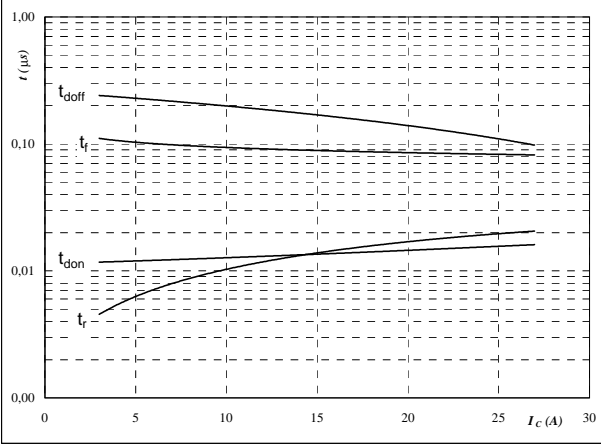


Brake Characteristics

Figure 9 IGBT

Typical switching times as a function of collector current

$t = f(I_C)$

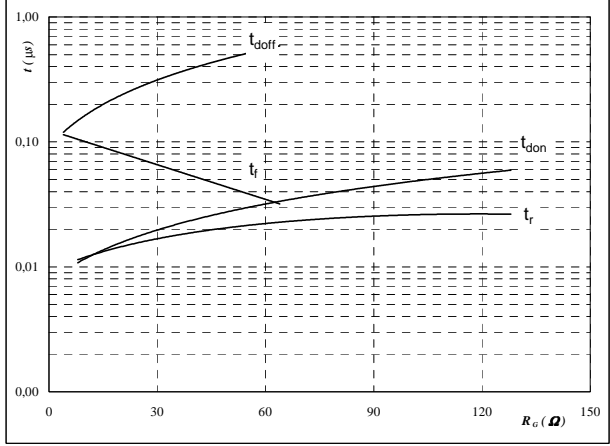


With an inductive load at
 $T_j = 125 \text{ }^\circ\text{C}$
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 15 \text{ V}$
 $R_{gon} = 16 \text{ } \Omega$
 $R_{goff} = 8 \text{ } \Omega$

Figure 10 IGBT

Typical switching times as a function of gate resistor

$t = f(R_G)$

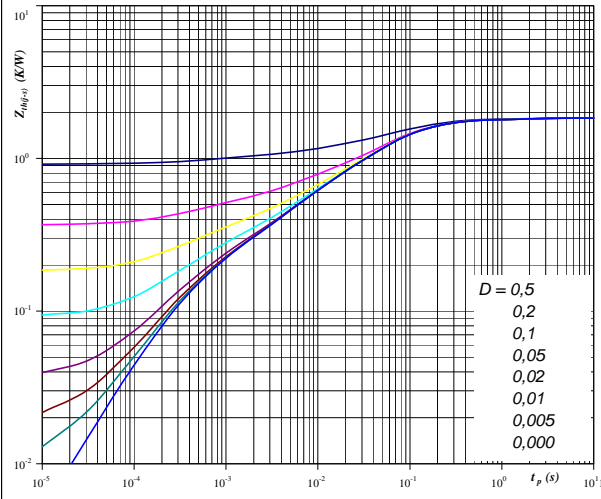


With an inductive load at
 $T_j = 125 \text{ }^\circ\text{C}$
 $V_{CE} = 300 \text{ V}$
 $V_{GE} = 15 \text{ V}$
 $I_C = 15 \text{ A}$

Figure 11 IGBT

IGBT transient thermal impedance as a function of pulse width

$Z_{thj-s} = f(t_p)$



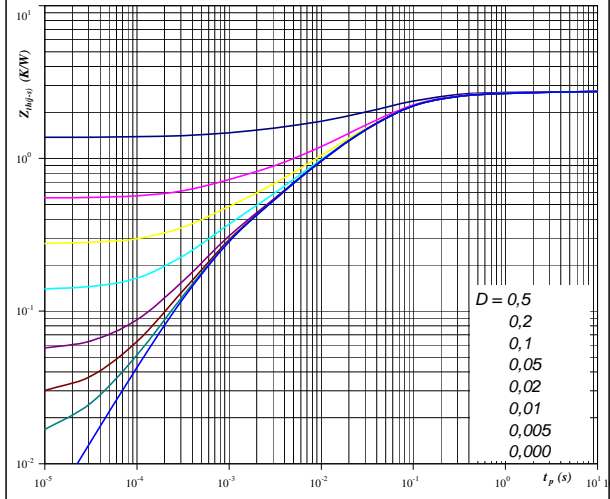
At $D = t_p / T$

$R_{thjH} = 1,83 \text{ K/W}$

Figure 12 FWD

FWD transient thermal impedance as a function of pulse width

$Z_{thj-s} = f(t_p)$



At $D = t_p / T$

$R_{thjH} = 2,75 \text{ K/W}$

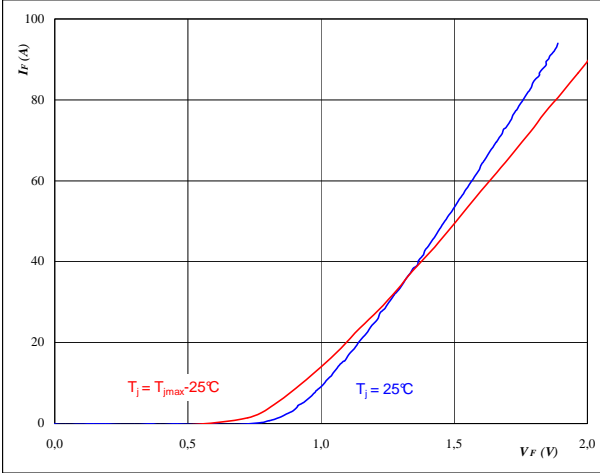


Rectifier Diode Characteristics

Figure 1 Diode

Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$

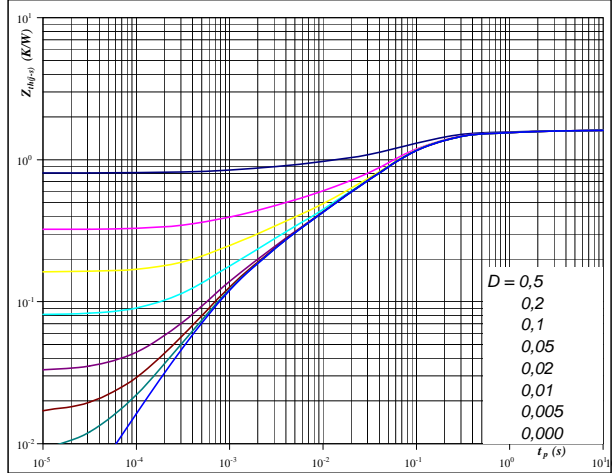


At $t_p = 250 \mu s$

Figure 2 Diode

Diode transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



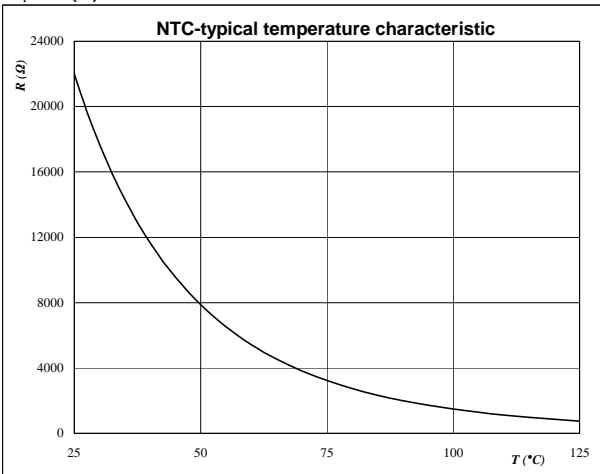
At $D = t_p / T$
 $R_{th(j-H)} = 1,61 \text{ K/W}$

Thermistor

Figure 1 Thermistor

Typical NTC characteristic as a function of temperature

$R_T = f(T)$





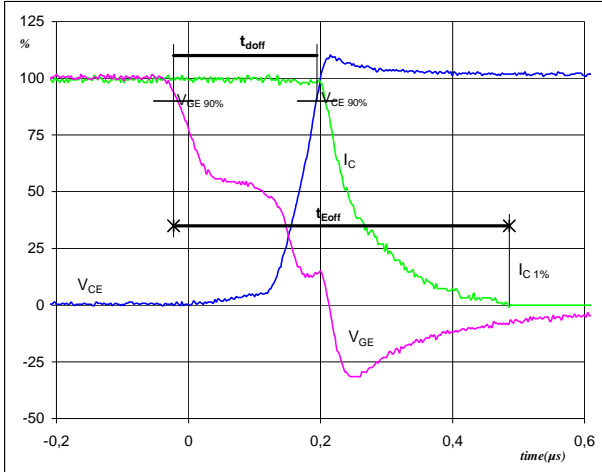
Switching Definitions Inverter

General conditions

T_j	=	125 °C
R_{gon}	=	16 Ω
R_{goff}	=	8 Ω

Figure 1 IGBT

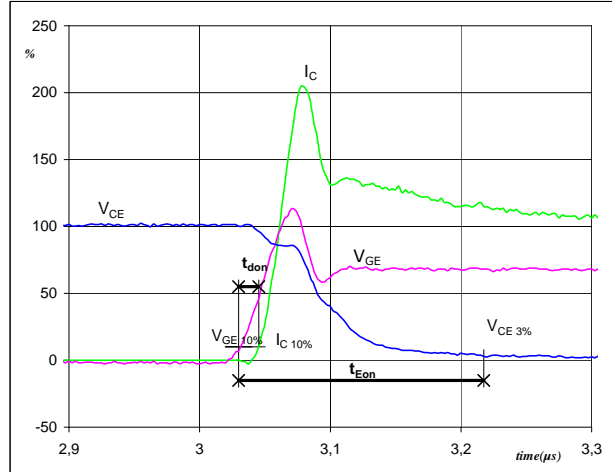
Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}
 (t_{Eoff} = integrating time for E_{off})



V_{GE} (0%) =	0	V
V_{GE} (100%) =	15	V
V_C (100%) =	300	V
I_C (100%) =	20	A
t_{doff} =	0,21	μs
t_{Eoff} =	0,51	μs

Figure 2 IGBT

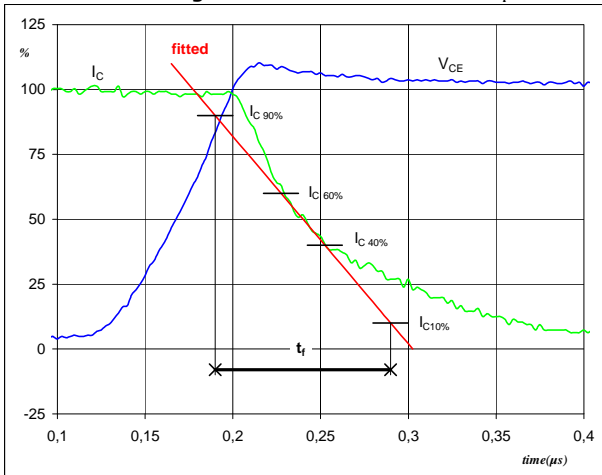
Turn-on Switching Waveforms & definition of t_{donr} , t_{Eon}
 (t_{Eon} = integrating time for E_{on})



V_{GE} (0%) =	0	V
V_{GE} (100%) =	15	V
V_C (100%) =	300	V
I_C (100%) =	20	A
t_{donr} =	0,01	μs
t_{Eon} =	0,19	μs

Figure 3 IGBT

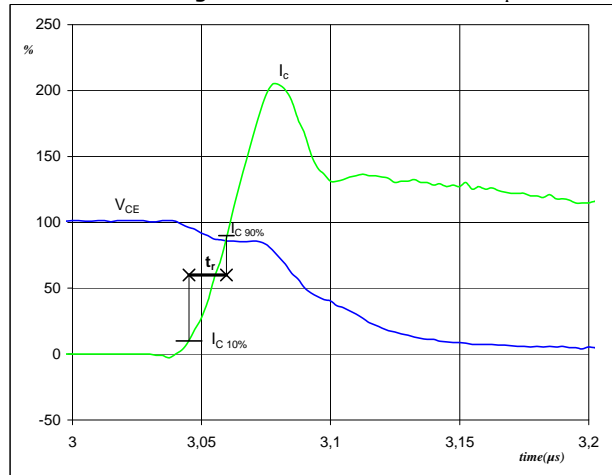
Turn-off Switching Waveforms & definition of t_f



V_C (100%) =	300	V
I_C (100%) =	20	A
t_f =	0,10	μs

Figure 4 IGBT

Turn-on Switching Waveforms & definition of t_r

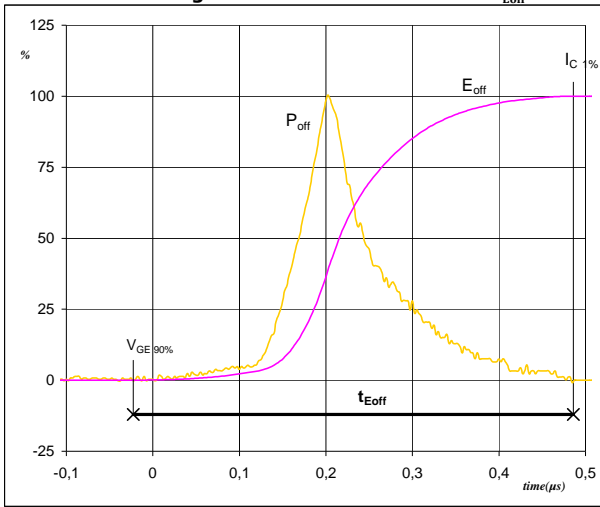


V_C (100%) =	300	V
I_C (100%) =	20	A
t_r =	0,02	μs



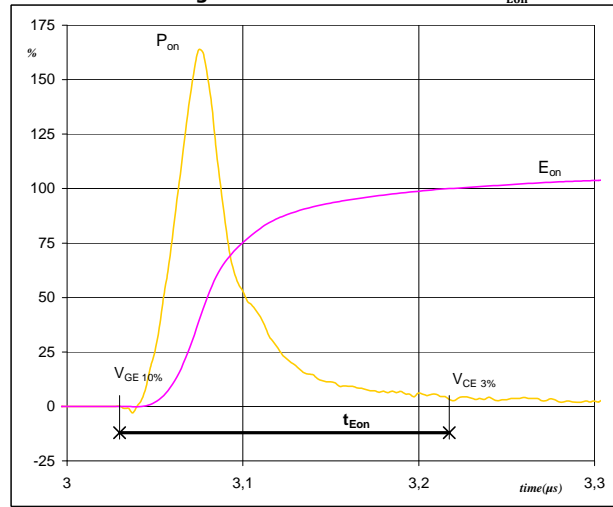
Switching Definitions Inverter

Figure 5 IGBT
Turn-off Switching Waveforms & definition of t_{Eoff}



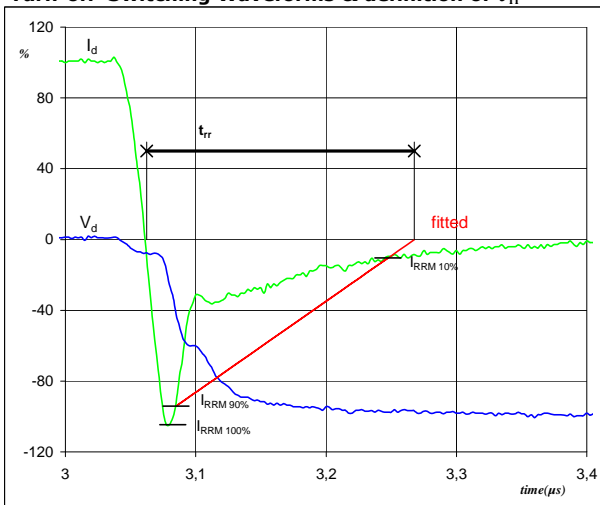
$P_{off} (100\%) = 5,99 \text{ kW}$
 $E_{off} (100\%) = 0,65 \text{ mJ}$
 $t_{Eoff} = 0,51 \text{ } \mu\text{s}$

Figure 6 IGBT
Turn-on Switching Waveforms & definition of t_{Eon}



$P_{on} (100\%) = 5,99 \text{ kW}$
 $E_{on} (100\%) = 0,43 \text{ mJ}$
 $t_{Eon} = 0,19 \text{ } \mu\text{s}$

Figure 7 FWD
Turn-off Switching Waveforms & definition of t_{rr}



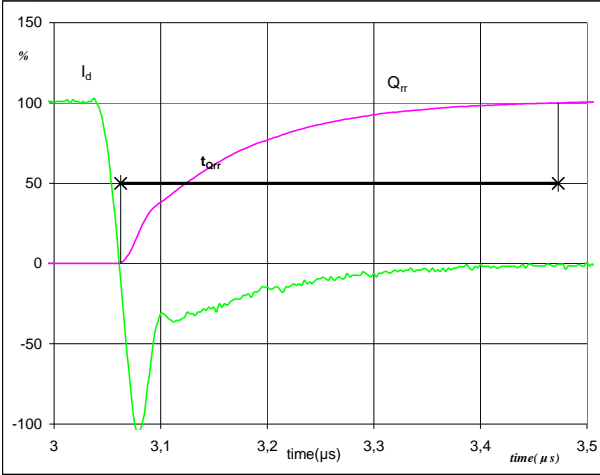
$V_d (100\%) = 300 \text{ V}$
 $I_d (100\%) = 20 \text{ A}$
 $I_{RRM} (100\%) = 21 \text{ A}$
 $t_{rr} = 0,19 \text{ } \mu\text{s}$



Switching Definitions Inverter

Figure 8 FWD

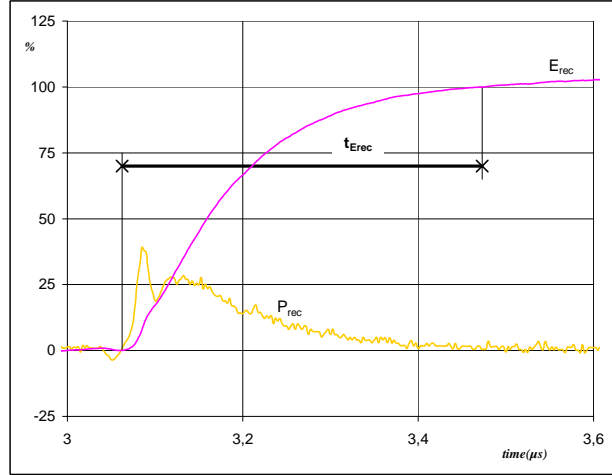
Turn-on Switching Waveforms & definition of t_{Qrr}
(t_{Qrr} = integrating time for Q_{rr})



I_d (100%) =	20	A
Q_{rr} (100%) =	1,35	μC
t_{Qrr} =	0,41	μs

Figure 10 FWD

Turn-on Switching Waveforms & definition of t_{Erec}
(t_{Erec} = integrating time for E_{rec})



P_{rec} (100%) =	5,99	kW
E_{rec} (100%) =	0,27	mJ
t_{Erec} =	0,41	μs



Ordering Code and Marking - Outline - Pinout

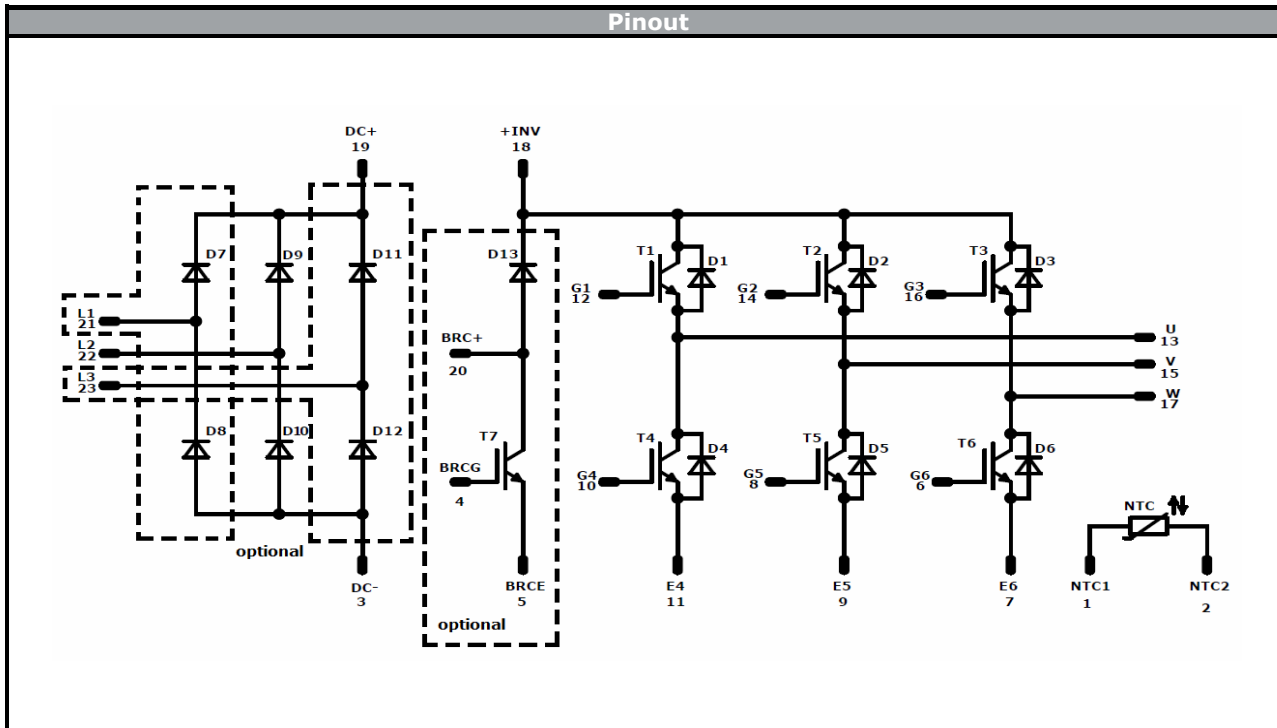
Ordering Code & Marking						
Version			Ordering Code			
without thermal paste 12mm housing with solder pins			V23990-P545-A28-PM			
with thermal paste 12mm housing with solder pins			V23990-P545-A28-/3/-PM			
without thermal paste 17mm housing with solder pins			V23990-P545-A29-PM			
without thermal paste 12mm housing 1 phase rectifier with solder pins			V23990-P545-B28-PM			
with thermal paste 12mm housing 1 phase rectifier with solder pins			V23990-P545-B28-/3/-PM			
with thermal paste 12mm housing 1 phase rectifier with solder pins			V23990-P545-B128-/3/-PM			
without thermal paste 17mm housing 1 phase rectifier with solder pins			V23990-P545-B129-PM			
with thermal paste 17mm housing 1 phase rectifier with solder pins			V23990-P545-B129-/3/-PM			
without thermal paste 17mm housing without brake with solder pins			V23990-P545-C29-PM			
without thermal paste 12mm housing 1 phase rectifier without brake with solder pins			V23990-P545-D28-PM			
with thermal paste 12mm housing 1 phase rectifier without brake with solder pins			V23990-P545-D28-/3/-PM			
without thermal paste 12mm housing without brake with solder pins			V23990-P545-C28-PM			
with thermal paste 12mm housing without brake with solder pins			V23990-P545-C28-/3/-PM			
	Text	VIN	Name&Ver	UL	Lot	Serial
		VIN	NNNNNNVV	UL	LLLLL	SSSS
	Datamatrix	Name&Ver	Serial	Date Code		
		NNNNNNVV	SSSS	WVVY		

Pin table				Outline	
Pin	X	Y	Function	<p>17 mm housing</p>	
1	25,5	2,7	NTC1		
2	25,5	0	NTC2		
3	22,8	0	-DC		
4	20,1	0	BRCG		
5	16,2	0	BRCE		
6	13,5	0	G6		
7	10,8	0	E6		
8	8,1	0	G5		
9	5,4	0	E5		
10	2,7	0	G4	<p>12 mm housing</p>	
11	0	0	E4		
12	0	19,8	G1		
13	0	22,5	U		
14	7,5	19,8	G2		
15	7,5	22,5	V		
16	15	19,8	G3		
17	15	22,5	W		
18	22,8	22,5	+INV		
19	25,5	22,5	+DC		
20	33,5	22,5	BRC+		
21	33,5	15	L1		
22	33,5	7,5	L2		
23	33,5	0	L3		

Pinout variation	
Module subtype	Not assembled pins
V23990-P545-A28-PM	-
V23990-P545-A29-PM	-
V23990-P545-B28-PM	21
V23990-P545-B128-PM	23
V23990-P545-B129-PM	23
V23990-P545-C29-PM	4, 5, 20
V23990-P545-D28-PM	4, 5, 20, 21
V23990-P545-C28-PM	4, 5, 20



Ordering Code and Marking - Outline - Pinout




Identification					
ID	Component	Voltage	Current	Function	Comment
T1,T2,T3,T4,T5,T6	IGBT	600V	20A	Inverter Switch	
D1,D2,D3,D4,D5,D6	FWD	600V	20A	Inverter Diode	
T7	IGBT	600V	15A	Brake Switch	
D13	FWD	600V	15A	Brake Diode	
D7,D8,D9,D10,D11,D12	Diode	1600V	25A	Rectifier Diode	
NTC	NTC			Thermistor	



Packaging instruction			
Standard packaging quantity (SPQ)	135	>SPQ Standard	<SPQ Sample

Handling instruction
Handling instructions for <i>flow</i> 0 packages see vincotech.com website.

Package data
Package data for <i>flow</i> 0 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
V23990-P545-x2x-D9-14	28 Aug. 2019	P545-C28 version added	1,19

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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